

ABSTRACT

(PROBLEM) To improve the productivity and the yield of a product, and to grind a semiconductor substrate so that it has almost uniform thickness.

(MEANS TO SOLVE THE PROBLEM) A protrusion 40 is formed on a semiconductor substrate 10 having a first area 20 and a second area 30 surrounding the first area 20, the protrusion 40 protruding above first area 20. A support 60 is disposed on a surface on which the protrusion 40 is formed, of the semiconductor substrate 10 so that a through hole 61 of the support 60 overlaps with the first area 20. The semiconductor substrate 10 is grinded from a surface opposite to the surface on which the protrusion 40 is formed.

(SELECTED FIGURE) FIG. 5